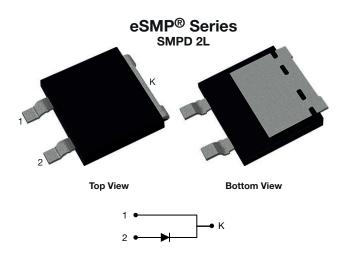
SE30DT12

Vishay General Semiconductor

Surface-Mount High Voltage Rectifier



www.vishay.com

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS				
I _{F(AV)}	30 A			
V _{RRM}	1200 V			
I _{FSM}	300 A			
V _F at I _F = 30 A (T _J = 150 °C)	1.01 V			
I _R	10 µA			
T _J max.	175 °C			
Package	SMPD 2L			
Circuit configuration	Single			

FEATURES

- · Creepage and clearance distance 3.6 mm minimum
- Very low profile typical height of 1.7 mm
- · Ideal for automated placement
- Oxide planar chip junction
- Low forward voltage drop
- AEC-Q101 qualified
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

- ON Board charger (OBC)
- Charging stations
- Bridge function

MECHANICAL DATA

Case: SMPD 2L

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test Polarity: as marked

MAXIMUM RATINGS ($T_A = 25 \text{ °C}$ unless otherwise noted)				
PARAMETER	SYMBOL	SE30DT12	UNIT	
Device marking code		SE30DT12	V	
Maximum repetitive peak reverse voltage	V _{RRM}	1200	V	
Maximum DC forward current	I _F ⁽¹⁾	30	A	
	I _F ⁽²⁾	3.5		
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I _{FSM}	300	A	
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +175	°C	

Notes

⁽¹⁾ With heatsink

⁽²⁾ Free air, mounted on recommended copper pad area

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HALOGEN

FREE



ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 15 A	– T _J = 25 °C	- V _F ⁽¹⁾	1.03	-	V
	I _F = 30 A			1.16	1.29	
	I _F = 15 A	T _J = 150 °C		0.87	-	
	I _F = 30 A			1.01	-	
Reverse current	Rated V _R	T _J = 25 °C	- I _R ⁽²⁾	-	10	μA
	naleu v _R	T _J = 150 °C		62	300	
Typical reverse recovery time	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$		t _{rr}	3.4	-	μs
Typical junction capacitance	4.0 V, 1 MHz		CJ	132	-	pF

Notes

⁽¹⁾ Pulse test: 300 µs pulse width, 1 % duty cycle

⁽²⁾ Pulse test: Pulse width \leq 40 ms

THERMAL CHARACTERISTICS ($T_A = 25$ °c unless otherwise noted)				
PARAMETER	SYMBOL	SE30DT12	UNIT	
Typical thermal resistance	R _{0JA} (1)(2)	52	°C/W	
Typical mermanesistance	R _{0JM} ⁽³⁾	1.5		

Notes

⁽¹⁾ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{0JA}$

(2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz. standard footprint

(3) Thermal resistance junction-to-mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SE30DT12-M3/I	0.52	l	2000 / reel	13" diameter plastic tape and reel
SE30DT12HM3/I (1)	0.52	I	2000 / reel	13" diameter plastic tape and reel

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

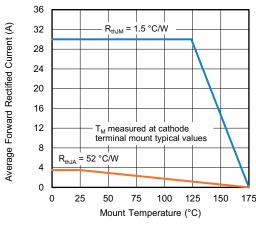


Fig. 1 - Forward Current Derating Curve

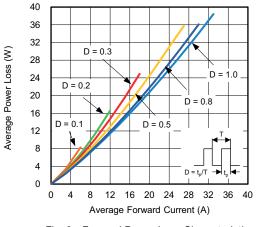


Fig. 2 - Forward Power Loss Characteristics

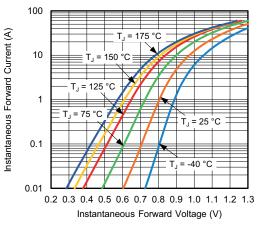


Fig. 3 - Typical Instantaneous Forward Characteristics

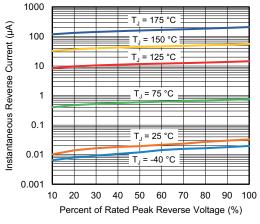
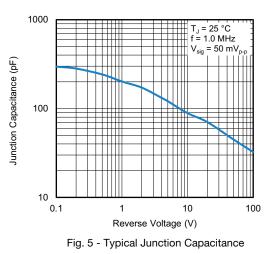
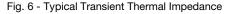


Fig. 4 - Typical Reverse Leakage Characteristics





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Transient Thermal Impedance (°C/W)

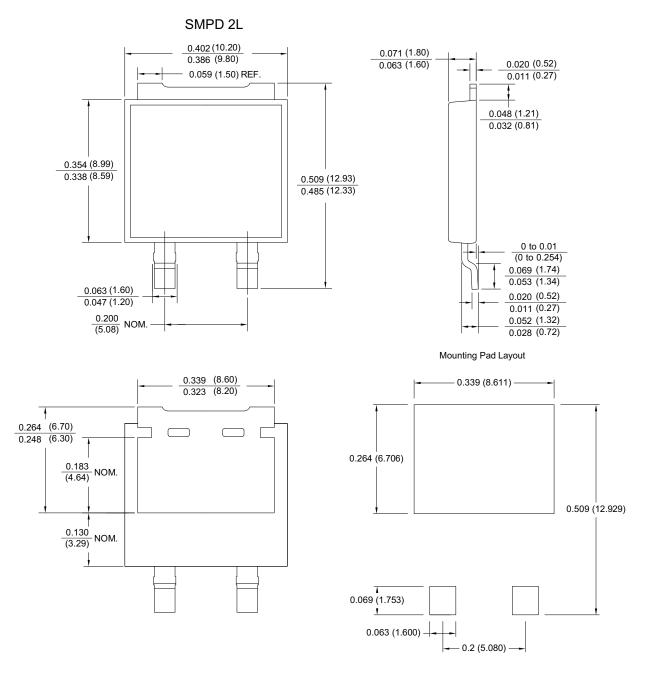
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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)



Note

• The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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